

# 2SA2082

## Silicon PNP epitaxial planar type

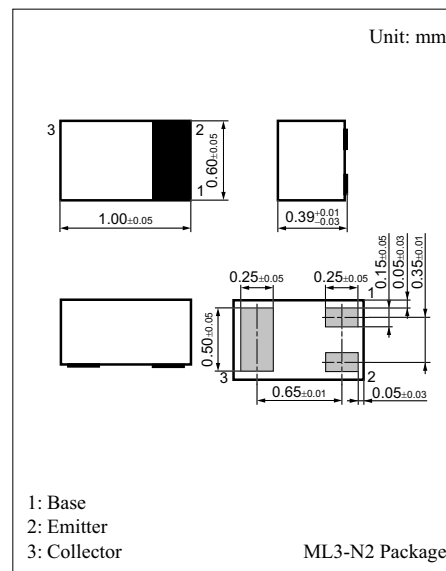
For high speed switching

### ■ Features

- High speed switching
- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Suitable for high-density mounting and downsizing of the equipment for ultraminiature leadless package  
Package: 0.6 mm × 1.0 mm (height 0.39 mm)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-10	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-10	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-4	V
Collector current	$I_C$	-50	mA
Peak collector current	$I_{CP}$	-100	mA
Collector power dissipation	$P_C$	100	mW
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{slg}$	-55 to +125	$^\circ\text{C}$

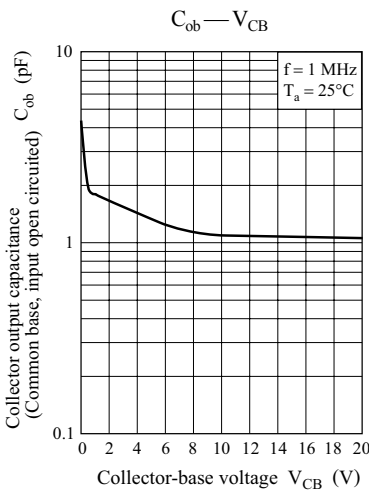
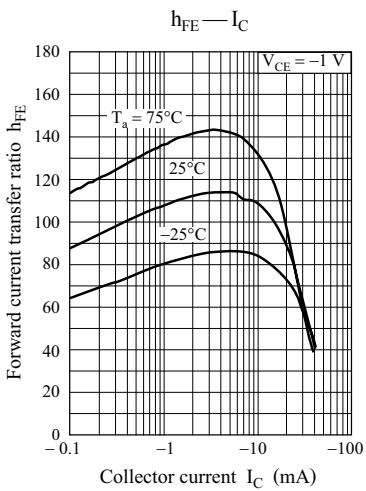
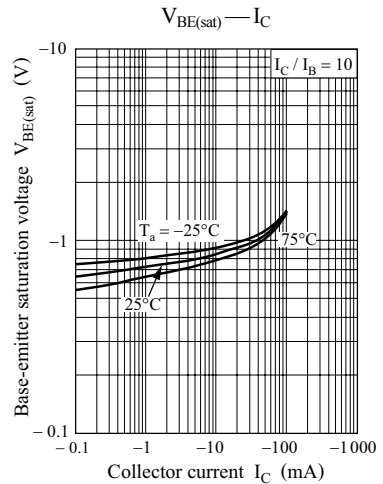
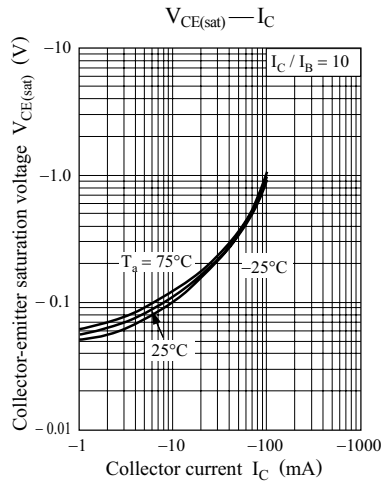
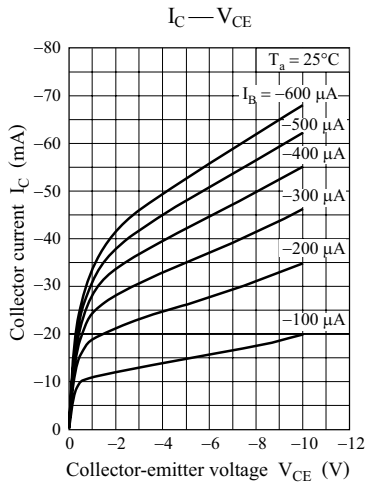
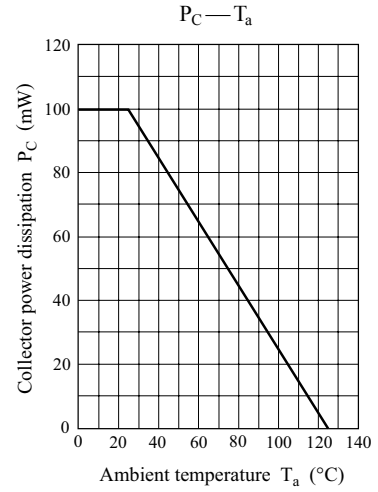
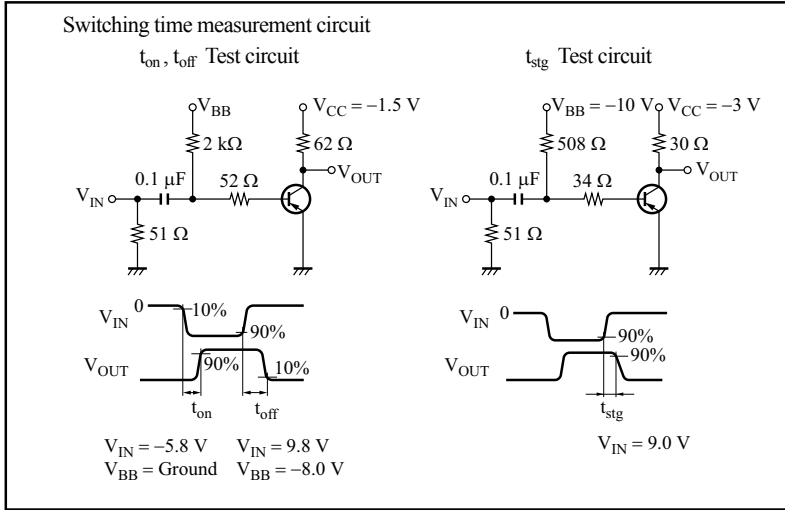


Marking Symbol : 4N

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -8\text{ V}, I_E = 0$			-0.1	$\mu\text{A}$
Emitter-base cut-off current (Collector open)	$I_{EBO}$	$V_{EB} = -3\text{ V}, I_C = 0$			-0.1	$\mu\text{A}$
Forward current transfer ratio	$h_{FE1}$	$V_{CE} = -1\text{ V}, I_C = -10\text{ mA}$	50		150	—
	$h_{FE2}$	$V_{CE} = -1\text{ V}, I_C = -1\text{ mA}$	30			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10\text{ mA}, I_B = -1\text{ mA}$		-0.1	-0.2	V
Transition frequency	$f_T$	$V_{CB} = -10\text{ V}, I_E = 10\text{ mA}, f = 200\text{ MHz}$	800	1 500		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = -5\text{ V}, I_E = 0, f = 1\text{ MHz}$		2.2		pF
Turn-on time	$t_{on}$	Switching time measurement circuit		12		ns
Turn-off time	$t_{off}$			20		ns
Storage time	$t_s$			19		ns

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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